LDBPF2300-1205

Multilayer Filter Combination

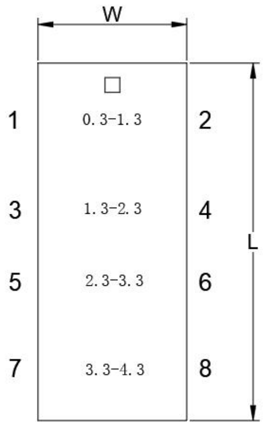
Features

- ● Multilayer monolithic construction yields high reliability
- ● Low insertion loss and small size SMD chip design
- ● Can simplify your complex tuning and circuit design
- ● LTCC process

Specifications

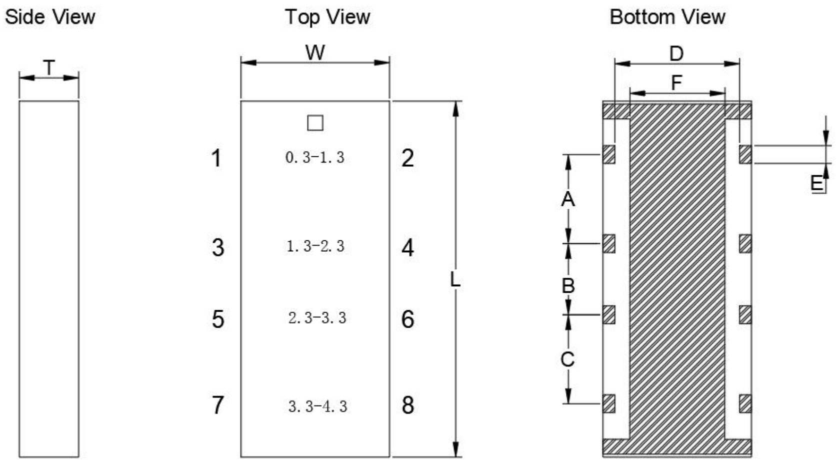
NO.	Specification				
		BPF_1	BPF_2	BPF_3	BPF_4
1	Frequency range (MHz)	300~1300	1300~2300	2300~3300	3300~4300
2	Insertion Loss (dB) @25℃	≤2	≤2.5	≤3	≤3.5
3	-1.2dB Bandwidth(MHz)	⩾1000	⩾1000	⩾1000	⩾1000
4	VSWR (In BW)	≤1.5	≤1.5	≤1.5	≤1.5
5	Attenuation(dBc)	≥40 @ DC~150 MHz	≥40 @ DC~1000 MHz	≥40 @ DC~2000 MHz	≥40 @ DC~3000 MHz
		≥40@ 1600~5000 MHz	≥40@2600~5000 MHz	≥ 40 @3600~5000 MHz	≥ 40 @4600~6000 MHz
6	Impedance (Ω)	50Ω			
Operating & Storage Condition (Component) Operation Temperature Range: -40℃ ~ +85℃ Storage Temperature Range: -40℃~ +85℃					
Storage Condition before Soldering (Included packaging material) Storage Temperature Range: +5 ~ +40 ℃ Humidity: 30 to 70% relative humidity					

Construction

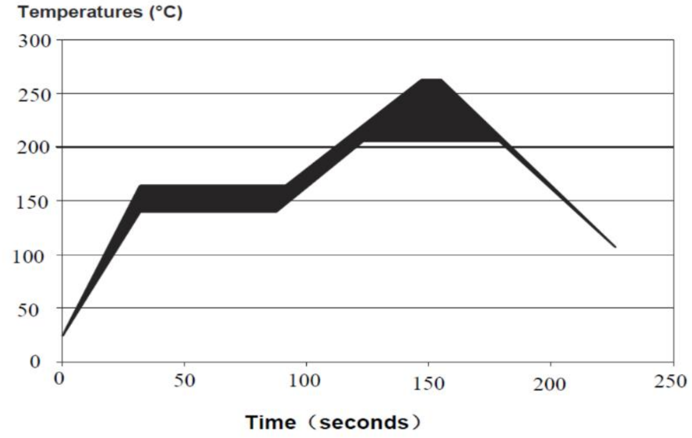


PIN	Connection	PIN	Connection
1	BPF 0.3-1.3_input Port	2	BPF 0.3-1.3_output Port
3	BPF 1.3-2.3_input Port	4	BPF 1.3-2.3_output Port
5	BPF 2.3-3.3_input Port	6	BPF 2.3-3.3_output Port
7	BPF 3.3-4.3_input Port	8	BPF 3.3-4.3_output Port

Dimensions

Figure	Symbol	Dimension (mm)
	L	12.00 ± 0.30
	W	5.00± 0.30
	T	2.00 MAX
	A	3.00± 0.15
	B	2.40 ± 0.15
	C	3.00± 0.15
	D	4.20± 0.15
	E	0.60± 0.15
	F	1.35± 0.15

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 ℃

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

*** After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.**